



# SOT2101-1

HVQFN76, thermal enhanced very thin quad flat package, no leads, 76 terminals, 0.4 mm pitch, 9 mm x 9 mm x 0.85 mm body

9 March 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN76
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-03-2014
<b>Manufacturer package code</b>	MV-A300073-00

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.9	9	9.1	mm
package width	8.9	9	9.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	76	-	



2 Package outline

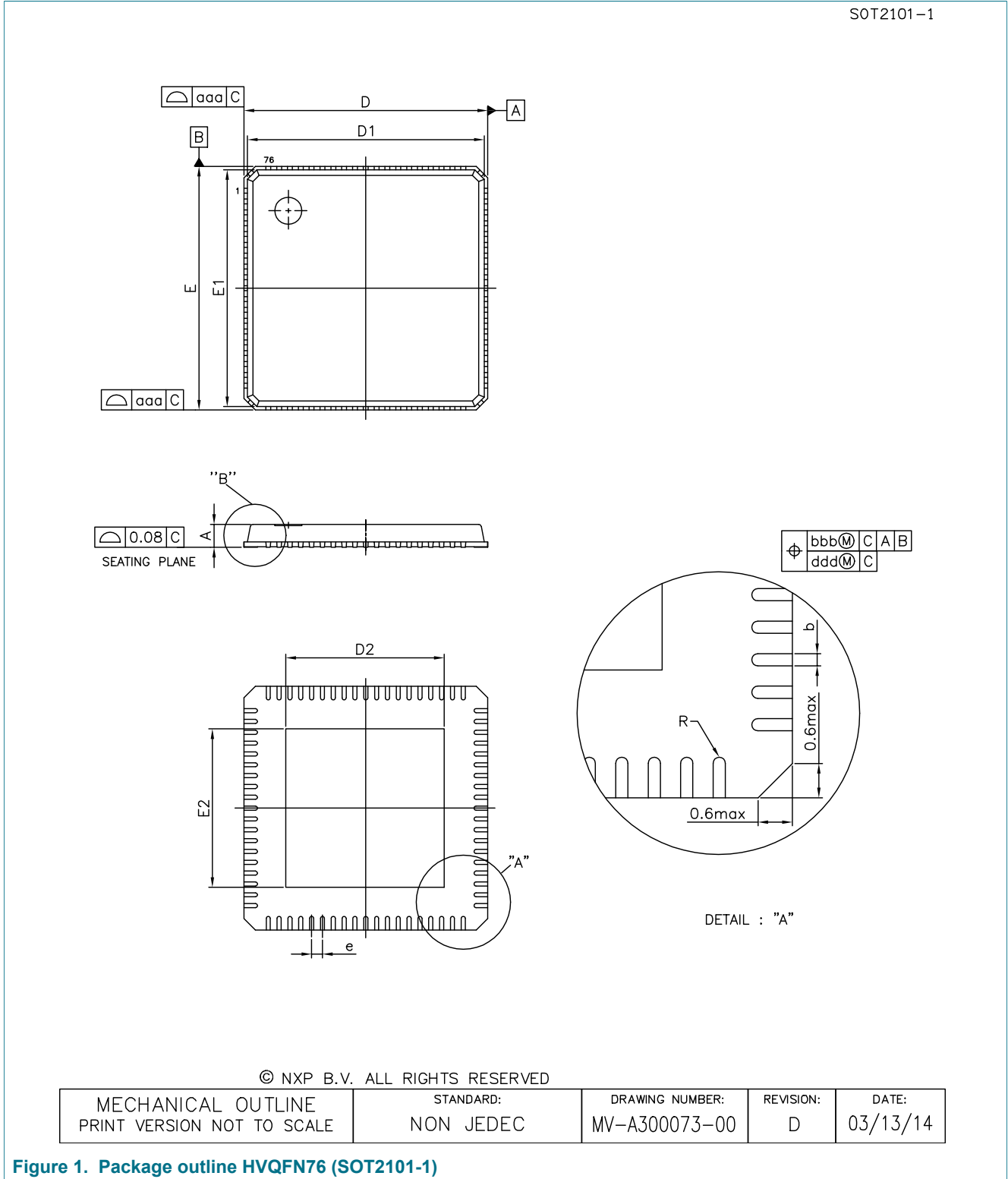
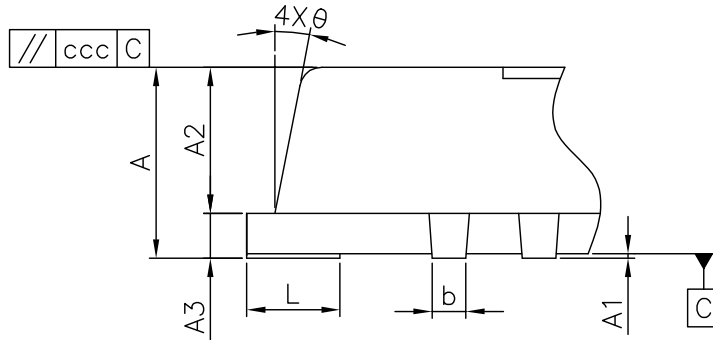


Figure 1. Package outline HVQFN76 (SOT2101-1)

HVQFN76, thermal enhanced very thin quad flat package, no leads, 76 terminals, 0.4 mm pitch, 9 mm x 9 mm x 0.85 mm body

SOT2101-1



DETAIL : "B"

Symbol	Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.85	1.00	0.031	0.033	0.039
A1	0.00	0.02	0.05	0.000	0.001	0.002
A2	---	0.65	1.00	---	0.026	0.039
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	9.00 BSC			0.354 BSC		
D1	8.75 BSC			0.344 BSC		
E	9.00 BSC			0.354 BSC		
E1	8.75 BSC			0.344 BSC		
e	0.40 BSC			0.016 BSC		
θ	0°	---	14°	0°	---	14°
R	0.075	---	---	0.003	---	---
aaa	---	---	0.15	---	---	0.006
bbb	---	---	0.10	---	---	0.004
ccc	---	---	0.10	---	---	0.004
ddd	---	---	0.05	---	---	0.002
chamfer	---	---	0.60	---	---	0.024

Exposed Die Pad Size / Lead length Options			
Option	Symbol	Dimension in mm	Dimension in inch
Option #1	D2	5.45 ± 0.20	0.215 ± 0.008
	E2	5.45 ± 0.20	0.215 ± 0.008
	L	0.50 ± 0.10	0.020 ± 0.004
Option #2	D2	3.80 ± 0.20	0.150 ± 0.008
	E2	3.80 ± 0.20	0.150 ± 0.008
	L	0.40 ± 0.10	0.016 ± 0.004
Option #3	D2	4.90 ± 0.20	0.193 ± 0.008
	E2	4.90 ± 0.20	0.193 ± 0.008
	L	0.40 ± 0.10	0.016 ± 0.004
Option #4	D2	5.82 ± 0.20	0.229 ± 0.008
	E2	6.33 ± 0.20	0.249 ± 0.008
	L	0.40 ± 0.10	0.016 ± 0.004

NOTE:

1. CONTROLLING DIMENSION : MILLIMETER
2. REFERENCE DOCUMENT: PROPOSED JEDEC MO-220.

© NXP B.V. ALL RIGHTS RESERVED

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV-A300073-00	REVISION: D	DATE: 03/13/14
--	------------------------	----------------------------------	----------------	-------------------

Figure 2. Package outline detail HVQFN76 (SOT2101-1)

### 3 Legal information

---

#### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

---

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4